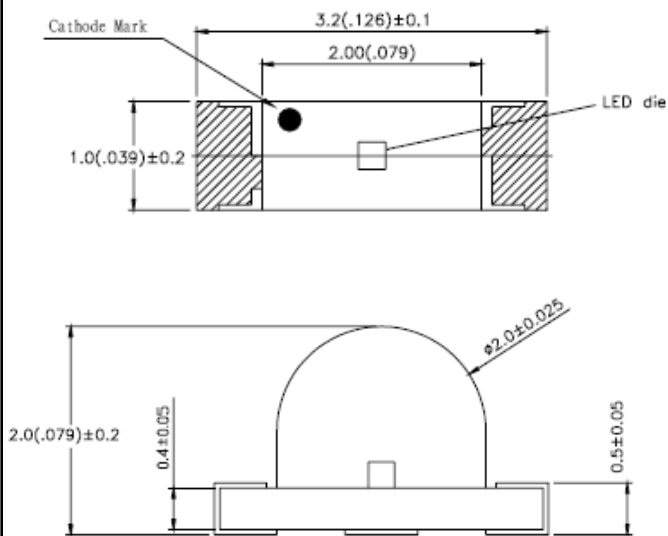


## SURFACE MOUNT CHIP LED LAMPS

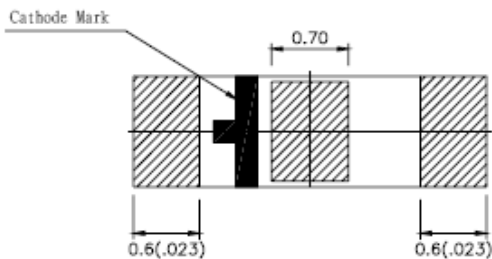
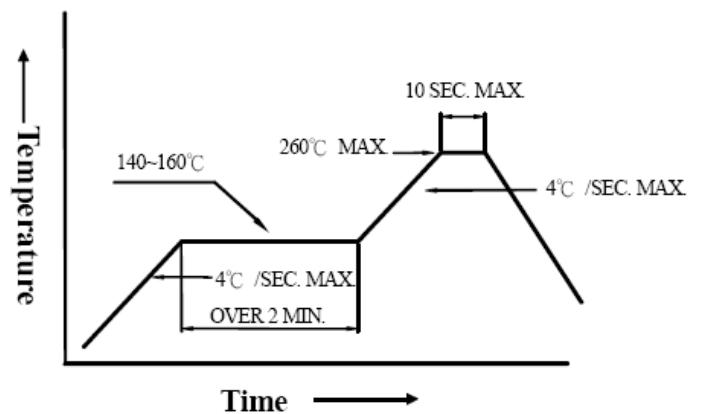
Right Angle Lens Yellow Green SMD Chip LED Lamps

Part Number: AL-HG034A

### Package outlines & Re-flow Profile



#### Reflow Temp/Time

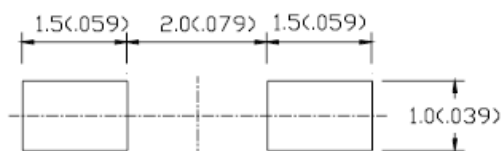


#### Soldering iron

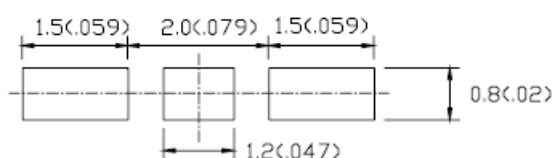
Basic spec is  $\leq 5$ sec when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1$ sec). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device should be under  $230^{\circ}\text{C}$ .

For Reflow Soldering

For upright mounting



For right anoge mounting



| ITEM                  | MATERIALS    |
|-----------------------|--------------|
| Resin (mold)          | Epoxy        |
| Lens color            | Water Clear  |
| Printed circuit board | BT           |
| Dice                  | GaP/GaP      |
| Emitted color         | Yellow Green |

#### NOTES:

- All dimensions are in millimeters (inches);
- Tolerances are  $\pm 0.1$ mm (0.004inch) unless otherwise noted.

**SURFACE MOUNT CHIP LED LAMPS**

Part Number: AL-HG034A

**ELECTRO-OPTICAL CHARACTERISTICS****(T<sub>A</sub>=25°C)**

| Parameter                               | Test Condition       | Symbol          | Value | Unit |
|---|----------------------|-----------------|-------|------|
| Viewing angle at 50% I <sub>v</sub>     | I <sub>F</sub> =10mA | 2 θ 1/2         | 100   | Deg  |
| Forward voltage (Typ.)                  | I <sub>F</sub> =20mA | V <sub>F</sub>  | 2.00  | V    |
| (Max.)                                  |                      |                 | 2.60  |      |
| Luminous intensity (Typ.)               | I <sub>F</sub> =20mA | I <sub>v</sub>  | 15.0  | mcd  |
| Wavelength                              | I <sub>F</sub> =20mA | λ <sub>p</sub>  | 571   | nm   |
|   |                      | λ <sub>d</sub>  | 570±5 |      |
| Spectral Line Half-Width                | I <sub>F</sub> =20mA | Δλ              | 30    | nm   |
| Peak pulsing current (1/10 duty f=1kHz) |                      | I <sub>FP</sub> | 100   | mA   |

**Absolute maximum ratings****(T<sub>A</sub>=25°C)**

| Parameter                   | Symbol              | Value    | Unit |
|-----------------------------|---------------------|----------|------|
| Forward current             | I <sub>F</sub>      | 30       | mA   |
| Reverse voltage             | V <sub>R</sub>      | 5        | V    |
| Reverse current             | I <sub>R</sub>      | 100      | μA   |
| Power Dissipation           | P <sub>D</sub>      | 100      | mW   |
| Operating temperature range | Top                 | -25 ~+80 | °C   |
| Storage temperature range   | T <sub>stg</sub>    | -30 ~+85 | °C   |
| Lead soldering temperature  | 260°C For 5 Seconds |          |      |

**SURFACE MOUNT CHIP LED LAMPS**

Part Number: AL-HG034A

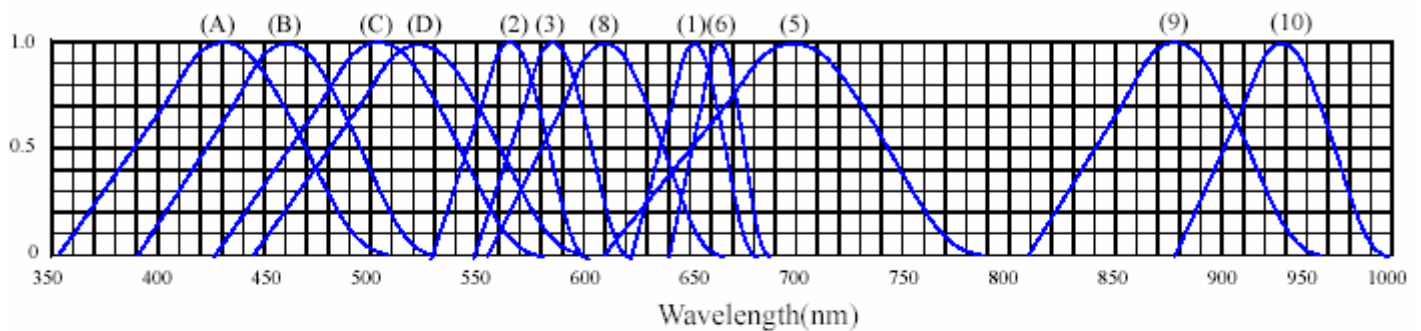
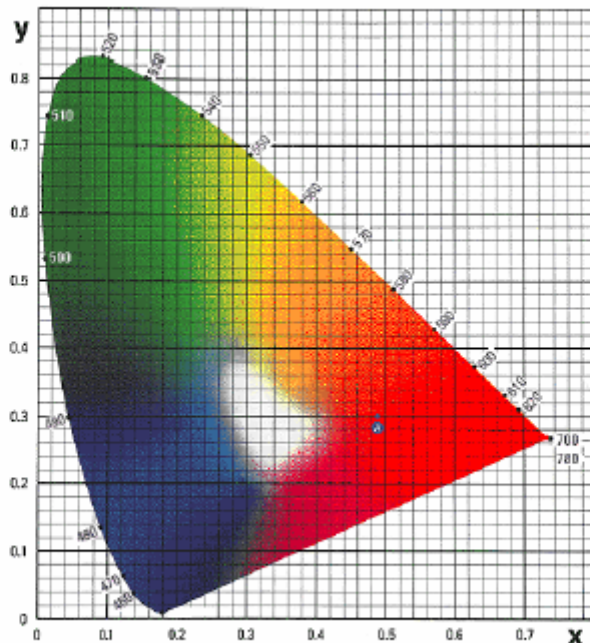
**Test items and results of reliability**

| Classification     | Test Item                              | Reference Standard  | Test Conditions   | Result |
|--------------------|--|---|---|--------|
| Endurance Test     | Operation Life                         | MIL-STD-750:1026<br>MIL-STD-883:1005<br>JIS-C-7021 :B-1                     | Connect with a power $I_f=20\text{mA}$<br>$T_a$ =Under room temperature<br>Test time=1,000hrs   | 0/20   |
|                    | High Temperature High Humidity Storage | MIL-STD-202:103B<br>JIS-C-7021 :B-11  | $T_a=+65^\circ\text{C}\pm 5^\circ\text{C}$<br>RH=90%-95%<br>Test time=240hrs  | 0/20   |
|                    | High Temperature Storage               | MIL-STD-883:1008<br>JIS-C-7021 :B-10  | High $T_a=+85^\circ\text{C}\pm 5^\circ\text{C}$<br>Test time=1,000hrs   | 0/20   |
|                    | Low Temperature Storage                | JIS-C-7021 :B-12  | Low $T_a=-35^\circ\text{C}\pm 5^\circ\text{C}$<br>Test time=1,000hrs  | 0/20   |
| Environmental Test | Temperature Cycling                    | MIL-STD-202:107D<br>MIL-STD-750:1051<br>MIL-STD-883:1010<br>JIS-C-7021 :A-4 | $-35^\circ\text{C} \sim +25^\circ\text{C} \sim +85^\circ\text{C} \sim +25^\circ\text{C}$<br>60min 20min 60min 20min<br>Test Time=5cycle | 0/20   |
|                    | Thermal Shock                          | MIL-STD-202:107D<br>MIL-STD-750:1051<br>MIL-STD-883:1011                    | $-35^\circ\text{C}\pm 5^\circ\text{C} \sim +85^\circ\text{C}\pm 5^\circ\text{C}$<br>20min 20min<br>Test Time=10cycle                    | 0/20   |
|                    | Solder Resistance                      | MIL-STD-202:201A<br>MIL-STD-750:2031<br>JIS-C-7021 :A-1                     | Preheating :<br>140°C -160°C, within 2 minutes.<br>Operation heating :<br>260°C (Max.), within 10seconds. (Max.)                        | 0/20   |

\* Refer to reliability test standard specification for in this line.

**SURFACE MOUNT CHIP LED LAMPS**

Part Number: AL-HG034A

**Typical Optical-Electrical Characteristic Curves**◆ **TYPICAL ELECTRICAL-OPTICAL CHARACTERISTICS CURVES**RELATIVE INTENSITY VS. WAVELENGTH( $\lambda_p$ )

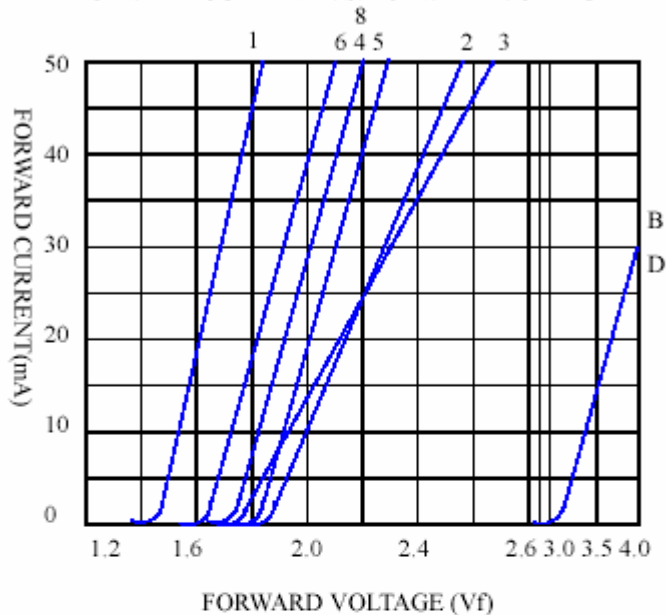
- |   |                                  |
|---|----------------------------------|
| (1) GaAsP/GaAs 655nm/Red                | (9)- GaAlAs 880nm                |
| (2) GaP 568nm/ Yellow Green             | (10)-GaAs/GaAs&GaAlAs/GaAs 940nm |
| (3) GaAsP/GaP 585nm/Yellow              | (A)- GaN 430nm/Blue              |
| (4) GaAsP/GaP 635nm/Orange & Hi-Eff Red | (B)- InGaN 470nm/Blue            |
| (5) GaP 700nm/Bright Red                | (C)- InGaN 502nm/Ultra Green     |
| (6) GaAlAs/GaAs 660nm/Super Red         | (D)- InGaN 523nm/Ultra Green     |
| (8) GaAsP/GaP 610nm/Super Red           |                                  |

**SURFACE MOUNT CHIP LED LAMPS**

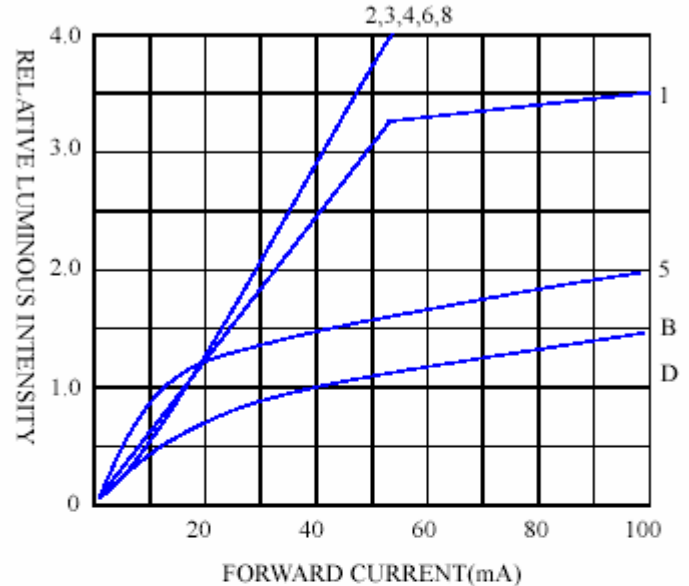
Part Number: AL-HG034A

**Typical Optical-Electrical Characteristic Curves**◆ **CHARACTERISTICS DIAGRAMS**

FORWARD CURRENT VS. FORWARD VOLTAGE



RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT



FORWARD CURRENT VS. AMBIENT TEMPERATURE

